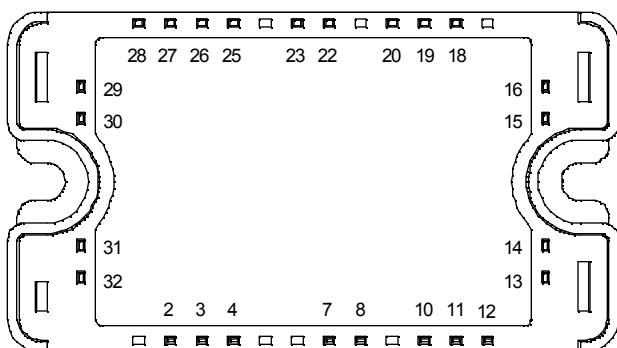
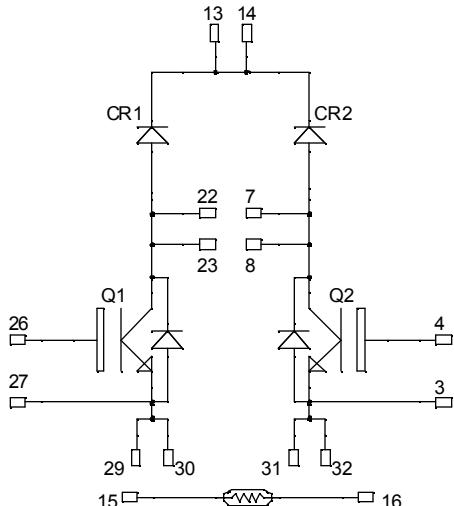


**Dual Boost chopper
Trench + Field Stop IGBT[®]
Power Module**

**V_{CES} = 600V
I_C = 30A @ T_c = 80°C**



All multiple inputs and outputs must be shorted together
Example: 13/14 ; 29/30 ; 22/23 ...

Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
V _{CES}	Collector - Emitter Breakdown Voltage	600	V
I _C	Continuous Collector Current	T _C = 25°C T _C = 80°C	50 30
I _{CM}	Pulsed Collector Current		
V _{GE}	Gate – Emitter Voltage	±20	V
P _D	Maximum Power Dissipation	T _C = 25°C T _J = 150°C	90 60A @ 550V
RBSOA	Reverse Bias Safe Operating Area		

 **CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handing Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

Application

- AC and DC motor control
- Switched Mode Power Supplies
- Power Factor Correction

Features

- Trench + Field Stop IGBT[®] Technology
 - Low voltage drop
 - Low tail current
 - Switching frequency up to 20 kHz
 - Soft recovery parallel diodes
 - Low diode VF
 - Low leakage current
 - Avalanche energy rated
 - RBSOA and SCSOA rated
- Kelvin emitter for easy drive
- Very low stray inductance
 - Symmetrical design
- High level of integration
- Internal thermistor for temperature monitoring

Benefits

- Stable temperature behavior
- Very rugged
- Solderable terminals for easy PCB mounting
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Easy paralleling due to positive TC of VCEsat
- Low profile
- Each leg can be easily paralleled to achieve a single boost of twice the current capability.
- RoHS Compliant

All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
I_{CES}	Zero Gate Voltage Collector Current	$V_{GE} = 0\text{V}$, $V_{CE} = 600\text{V}$				250	μA
$V_{CE(\text{sat})}$	Collector Emitter Saturation Voltage	$V_{GE} = 15\text{V}$	$T_j = 25^\circ\text{C}$		1.5	1.9	V
		$I_C = 30\text{A}$	$T_j = 150^\circ\text{C}$		1.7		
$V_{GE(\text{th})}$	Gate Threshold Voltage	$V_{GE} = V_{CE}$, $I_C = 400\mu\text{A}$		5.0	5.8	6.5	V
I_{GES}	Gate – Emitter Leakage Current	$V_{GE} = 20\text{V}$, $V_{CE} = 0\text{V}$				300	nA

Dynamic Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
C_{ies}	Input Capacitance	$V_{GE} = 0\text{V}$ $V_{CE} = 25\text{V}$ $f = 1\text{MHz}$		1600			pF
C_{oes}	Output Capacitance			110			
C_{res}	Reverse Transfer Capacitance			50			
$T_{d(on)}$	Turn-on Delay Time	$V_{GE} = \pm 15\text{V}$ $V_{Bus} = 300\text{V}$ $I_C = 30\text{A}$ $R_G = 10\Omega$	Inductive Switching (25°C)	110			ns
T_r	Rise Time			45			
$T_{d(off)}$	Turn-off Delay Time			200			
T_f	Fall Time			40			
$T_{d(on)}$	Turn-on Delay Time	$V_{GE} = \pm 15\text{V}$ $V_{Bus} = 300\text{V}$ $I_C = 30\text{A}$ $R_G = 10\Omega$	Inductive Switching (150°C)	120			ns
T_r	Rise Time			50			
$T_{d(off)}$	Turn-off Delay Time			250			
T_f	Fall Time			60			
E_{on}	Turn-on Switching Energy	$V_{GE} = \pm 15\text{V}$	$T_j = 25^\circ\text{C}$	0.16			mJ
		$V_{Bus} = 300\text{V}$	$T_j = 150^\circ\text{C}$	0.3			
E_{off}	Turn-off Switching Energy	$I_C = 30\text{A}$	$T_j = 25^\circ\text{C}$	0.7			mJ
		$R_G = 10\Omega$	$T_j = 150^\circ\text{C}$	1.05			

Chopper diode ratings and characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit	
V_{RRM}	Maximum Peak Repetitive Reverse Voltage			600			V	
I_{RM}	Maximum Reverse Leakage Current	$V_R = 600\text{V}$	$T_j = 25^\circ\text{C}$			250	μA	
			$T_j = 150^\circ\text{C}$			500		
I_F	DC Forward Current		$T_c = 80^\circ\text{C}$		30		A	
V_F	Diode Forward Voltage	$I_F = 30\text{A}$ $V_{GE} = 0\text{V}$	$T_j = 25^\circ\text{C}$		1.6	2	V	
			$T_j = 150^\circ\text{C}$		1.5			
t_{rr}	Reverse Recovery Time	$I_F = 30\text{A}$ $V_R = 300\text{V}$ $di/dt = 1800\text{A}/\mu\text{s}$	$T_j = 25^\circ\text{C}$		100		ns	
			$T_j = 150^\circ\text{C}$		150			
Q_{rr}	Reverse Recovery Charge		$T_j = 25^\circ\text{C}$		1.5		μC	
			$T_j = 150^\circ\text{C}$		3.1			
E_r	Reverse Recovery Energy		$T_j = 25^\circ\text{C}$		0.34		mJ	
			$T_j = 150^\circ\text{C}$		0.75			

Temperature sensor NTC (see application note APT0406 on www.microsemi.com for more information).

Symbol Characteristic
Min Typ Max Unit

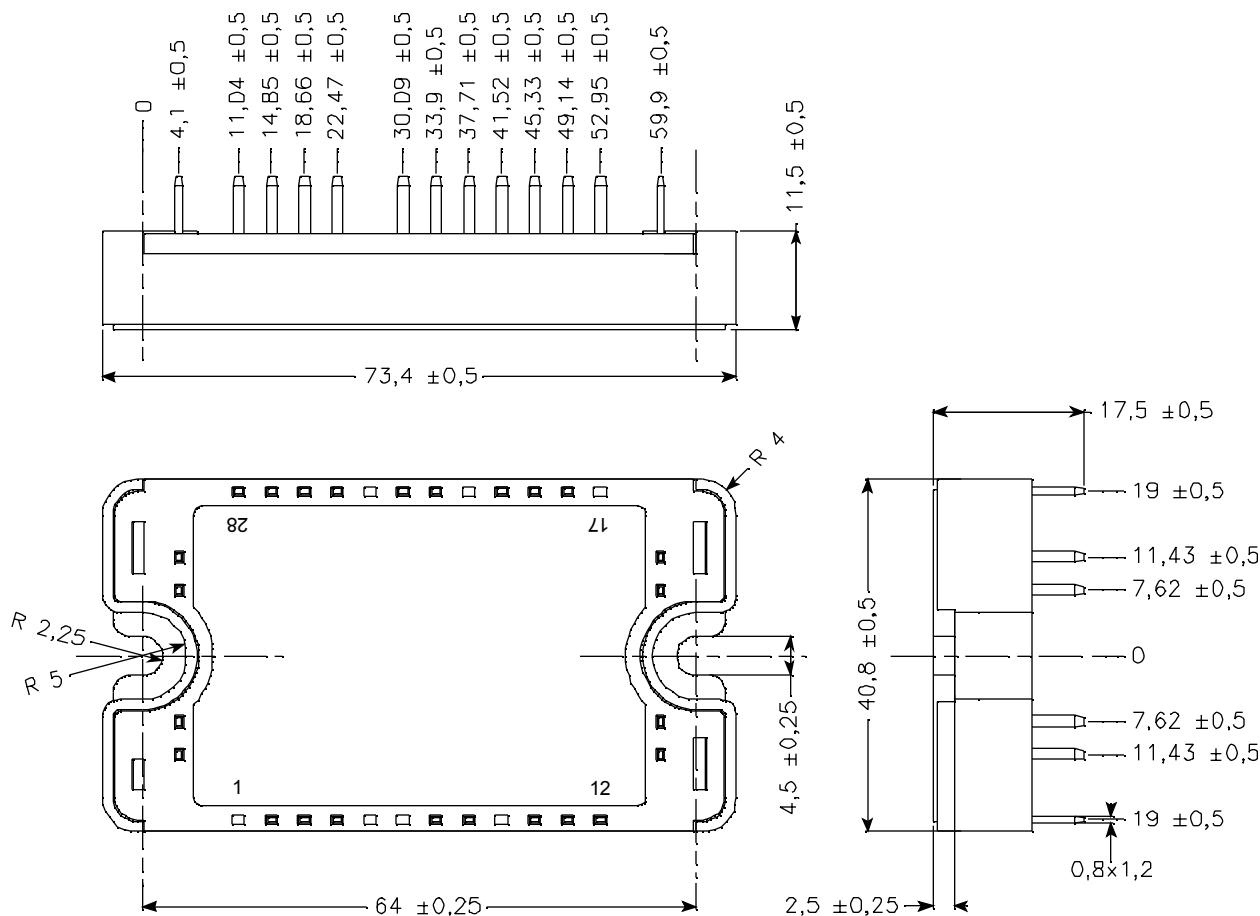
R ₂₅	Resistance @ 25°C		50		kΩ
B _{25/85}	T ₂₅ = 298.15 K		3952		K

$$R_T = \frac{R_{25}}{\exp\left[B_{25/85}\left(\frac{1}{T_{25}} - \frac{1}{T}\right)\right]}$$

T: Thermistor temperature
R_T: Thermistor value at T

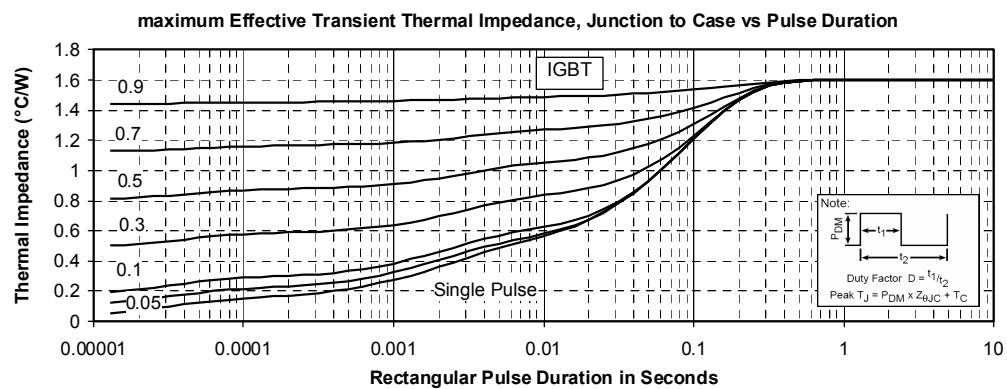
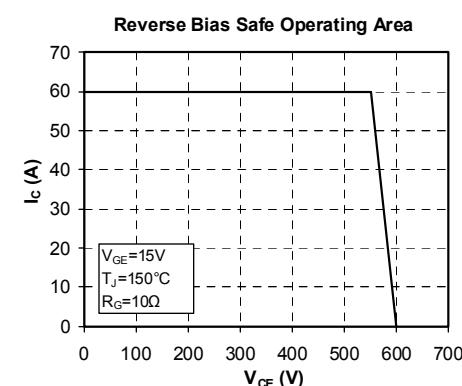
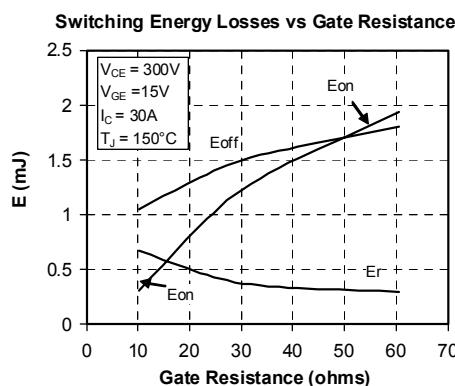
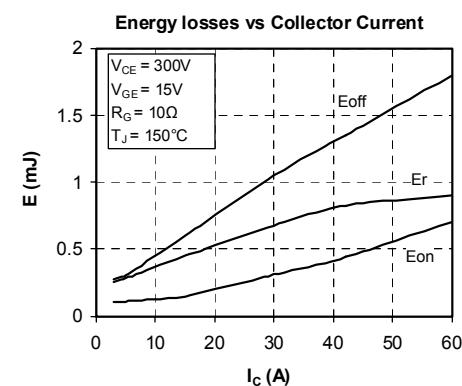
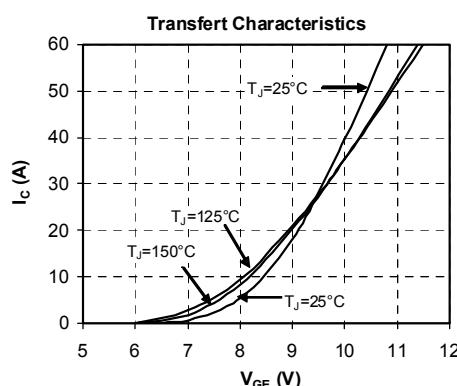
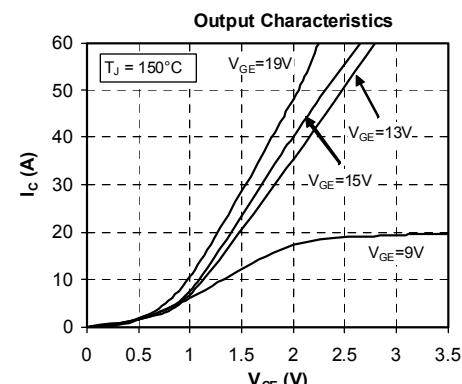
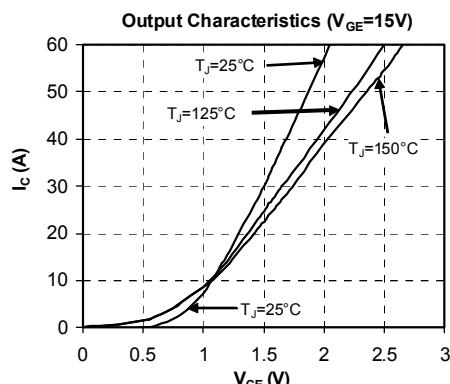
Thermal and package characteristics
Symbol Characteristic
Min Typ Max Unit

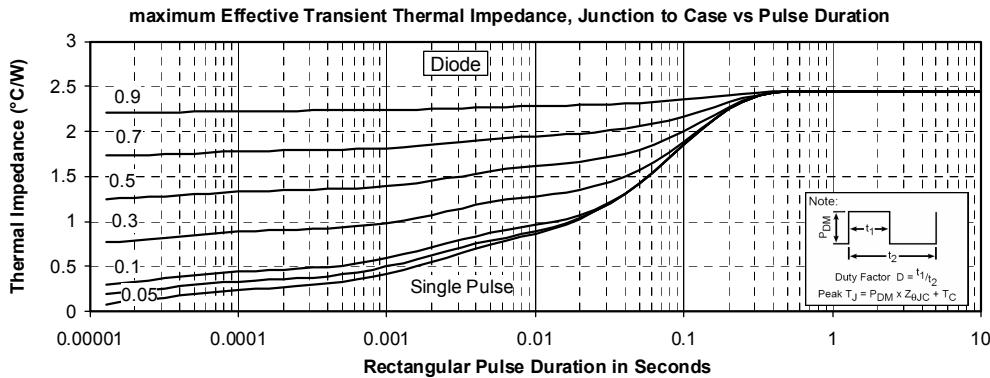
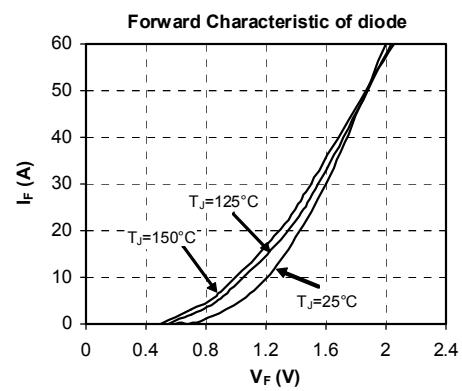
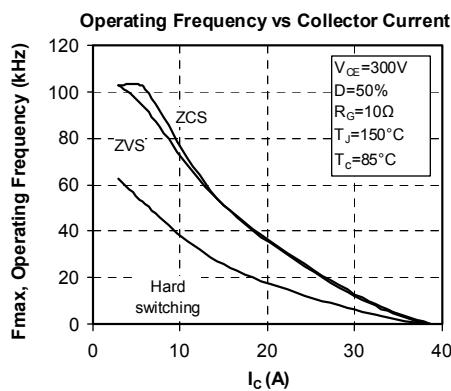
R _{thJC}	Junction to Case Thermal Resistance	IGBT		1.6	°C/W
		Diode		2.45	
V _{ISOL}	RMS Isolation Voltage, any terminal to case t = 1 min, I isol < 1mA, 50/60Hz	2500			V
T _J	Operating junction temperature range	-40		175	
T _{STG}	Storage Temperature Range	-40		125	°C
T _C	Operating Case Temperature	-40		100	
Torque	Mounting torque	To heatsink	M4	2.5	4.7
Wt	Package Weight			110	g

SP3 Package outline (dimensions in mm)

See application note 1901 - Mounting Instructions for SP3 Power Modules on www.microsemi.com



Typical Performance Curve





Microsemi reserves the right to change, without notice, the specifications and information contained herein

Microsemi's products are covered by one or more of U.S patents 4,895,810 5,045,903 5,089,434 5,182,234 5,019,522 5,262,336 6,503,786 5,256,583 4,748,103 5,283,202 5,231,474 5,434,095 5,528,058 and foreign patents pending. All Rights Reserved.